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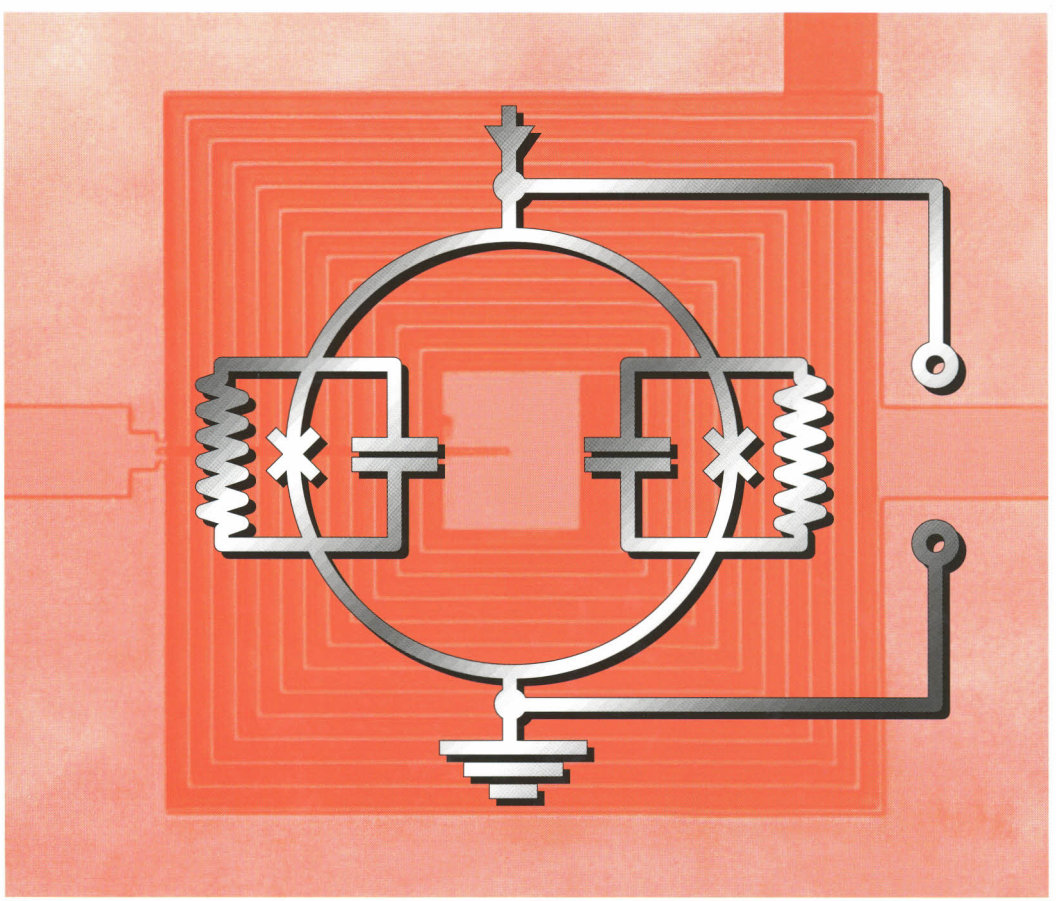
The SQUID Handbook

Vol. I Fundamentals and Technology of SQUIDs and SQUID Systems



Contents

Preface *XI*

1 Introduction *1*
1.1 The Beginning *2*
1.2 Subsequent Developments *5*
1.3 The dc SQUID: A First Look *7*
1.4 The rf SQUID: A First Look *12*
1.5 Cryogenics and Systems *16*
1.6 Instruments: Amplifiers, Magnetometers and Gradiometers *17*
1.7 Applications *21*
1.8 Challenges and Perspectives *24*
1.9 Acknowledgment *26*

2 SQUID Theory *29*
2.1 Josephson Junctions *30*
2.1.1 RCSJ Model *31*
2.1.2 Thermal Noise *37*
2.1.3 The $1/f$ Noise (I_0, R fluctuations) *41*
2.2 Theory of the dc SQUID *43*
2.2.1 Introduction *43*
2.2.2 Basic Equations, dc SQUID Potential *44*
2.2.3 Thermal Fluctuations *50*
2.2.3.1 General Considerations *50*
2.2.3.2 Numerical Simulations (Langevin Equation) *53*
2.2.3.3 Analytical Theory of the dc SQUID *59*
2.2.4 Effect of Asymmetry *65*
2.3 Theory of the rf SQUID *70*
2.3.1 Introduction *70*
2.3.2 SQUID Potential and the Equation of Motion for the Phase Difference *72*
2.3.3 Unitary Theory for Output Signal and Noise *76*
2.3.4 Noise as a Small Perturbation *83*
2.3.4.1 Introduction *83*

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2.3.4.2 Adiabatic Operation; Hysteretic Phase Diagram *84*
2.3.4.3 Non-adiabatic Regime *86*

3 SQUID Fabrication Technology *93*
3.1 Junction Electrode Materials and Tunnel Barriers *94*
3.2 Low-temperature SQUID Devices *96*
3.2.1 Refractory Junction Electrodes *96*
3.2.2 Tunnel Barrier Technology *97*
3.2.3 Deposition Techniques *98*
3.2.4 Junction Definition *101*
3.2.5 Dielectric Insulation *102*
3.2.6 Patterning Techniques *103*
3.2.7 Passive Components for Device Fabrication *105*
3.2.8 Integrated SQUID Fabrication Process *105*
3.3 High-temperature SQUID Devices *107*
3.3.1 General Requirements and Problems *107*
3.3.2 Thin-film Deposition *108*
3.3.3 Patterning Techniques *110*
3.3.4 Junction Fabrication *112*
3.3.5 Fabrication of Single-layer Devices *115*
3.3.6 Fabrication of Multilayer Devices *116*
3.3.7 Device Passivation and Encapsulation *118*
3.4 Future Trends *118*

4 SQUID Electronics *127*
4.1 General *128*
4.2 Basic Principle of a Flux-locked Loop *128*
4.2.1 Linearization of the Transfer Function *128*
4.2.2 Noise and Dynamic Behavior *131*
4.2.3 Integrator Types *135*
4.3 The dc SQUID Readout *137*
4.3.1 Fundamentals *137*
4.3.2 Methods to Suppress Preamplifier Noise *139*
4.3.2.1 Flux Modulation *139*
4.3.2.2 Additional Positive Feedback *141*
4.3.3 Methods to Suppress $1/f$ Noise *143*
4.3.4 Further Readout Concepts *148*
4.3.4.1 Two–stage Configuration *148*
4.3.4.2 Series SQUID Arrays *149*
4.3.4.3 Relaxation Oscillation SQUIDs *150*
4.3.4.4 Digital SQUIDs *152*
4.4 The rf SQUID Readout *155*
4.4.1 General *155*
4.4.2 Basic Building Blocks of rf SQUID Readout Electronics *155*
4.4.3 Construction of the Tank Circuit *157*

4.4.4 Coupling of the Tank Circuit to the Transmission Line *159*
4.4.5 Cryogenic Preamplifiers *160*
4.4.6 Optimization for Maximum Sensitivity *162*
4.4.7 Multiplexed Readouts for Multichannel rf SQUID Systems *164*
4.5 Trends in SQUID Electronics *165*

5 Practical DC SQUIDS: Configuration and Performance *171*
5.1 Introduction *172*
5.2 Basic dc SQUID Design *175*
5.2.1 Uncoupled SQUIDs *175*
5.2.2 Coupled SQUIDs *177*
5.3 Magnetometers *186*
5.3.1 Overview *186*
5.3.2 Magnetometers for High Spatial Resolution *187*
5.3.3 Magnetometers for High Field Resolution *188*
5.4 Gradiometers *193*
5.4.1 Overview *193*
5.4.2 Thin-Film Planar Gradiometers *195*
5.4.3 Wire-Wound Axial Gradiometers *198*
5.5 $1/f$ Noise and Operation in Ambient Field *200*
5.5.1 General Remarks on $1/f$ Noise *200*
5.5.2 Critical Current Fluctuations *200*
5.5.3 Thermally Activated Motion of Vortices *201*
5.5.4 Generation of vortices *203*
5.5.5 Reduction of $1/f$ Noise Generated by Vortex Motion *205*
5.5.5.1 Overview *205*
5.5.5.2 Vortex pinning *205*
5.5.5.3 Narrow Linewidth Device Structures *206*
5.5.5.4 Flux Dams *207*
5.6 Other Performance Degrading Effects *208*
5.6.1 Hysteresis *208*
5.6.2 Radio-Frequency Interference *209*
5.6.3 Temperature Fluctuations and Drift *210*

6 Practical RF SQUIDs: Configuration and Performance *219*
6.1 Introduction *220*
6.2 Rf SQUID Magnetometers *220*
6.2.1 Practical Device Optimization *220*
6.2.2 Low-Temperature rf SQUID Magnetometers *223*
6.2.2.1 Low-Temperature Bulk Magnetometers *223*
6.2.2.2 Low-Temperature Thin-Film Magnetometers *226*
6.2.3 High-Temperature rf SQUID Magnetometers *228*
6.2.3.1 Technological Limitations *228*
6.2.3.2 Bulk High-T_c Magnetometers *229*
6.2.3.3 Early Thin-Film High-T_c Magnetometers *229*

6.2.3.4 Magnetometers with Coplanar Resonators *230*
6.2.3.5 Magnetometers with Dielectric Resonators *234*
6.2.3.6 Thin-Film HTS Magnetometers with Flux Transformers *235*
6.3 Rf SQUID Gradiometers *236*
6.3.1 Low-Temperature Gradiometers *236*
6.3.2 High-Temperature Gradiometers *236*
6.3.2.1 Hardware rf SQUID Gradiometers *236*
6.3.2.2 Electronic rf SQUID gradiometers *237*
6.4 Low-Frequency Excess Noise in rf SQUIDs *237*
6.5 Response of rf SQUIDs to High-Frequency Electromagnetic Interference *239*
6.6 Characterization and Adjustment of rf SQUIDs *241*
6.7 The rf SQUID versus the dc SQUID *244*
6.8 Concluding Remarks and Outlook *246*

7 SQUID System Issues *251*
7.1 Introduction *254*
7.2 Cryogenics *255*
7.2.1 Introduction *255*
7.2.2 Liquid Cryogen Cooling (Cryostats) *256*
7.2.3 Cryogenic Refrigerators (Cryocoolers) *258*
7.2.3.1 Introduction *258*
7.2.3.2 Joule–Thomson Coolers *259*
7.2.3.3 Stirling Coolers *260*
7.2.3.4 Gifford–McMahon Coolers *261*
7.2.3.5 Pulse-tube Coolers *262*
7.2.3.6 Comparison of Cryocoolers *264*
7.2.3.7 Trends in Cryocooling *265*
7.2.4 Cryostat or Cryocooler? *266*
7.2.5 Cryocooler-interference Reduction *267*
7.2.5.1 Interference Mechanisms *267*
7.2.5.2 Time Separation *268*
7.2.5.3 Space Separation *268*
7.2.5.4 Low-noise Coolers *269*
7.2.5.5 Noise Suppression Techniques *269*
7.2.6 Material Properties *270*
7.3 Cabling and Electronics *272*
7.3.1 Shielding and Filtering of Noise Sources *272*
7.3.1.1 Introduction to Shielding Effectiveness *272*
7.3.1.2 Absorption *273*
7.3.1.3 Reflection *274*
7.3.1.4 High-frequency Shielding *276*
7.3.1.5 Low-frequency Shielding *277*
7.3.1.6 Filtering in an Unshielded Urban Environment *281*

7.3.1.7 Determination of Low-frequency Shielding, Filtering or Noise Cancellation Requirements *281*
7.3.2 Electronics and Cables *283*
7.3.2.1 RF Screening of Electronics *283*
7.3.2.2 Cables and Conductors *284*
7.3.2.3 Cable Junctions, Terminations, Connectors and Grounding *285*
7.3.2.4 Crosstalk *286*
7.3.2.5 Power Consumption and Supply *287*
7.3.2.6 Choice of SQUIDs and Electronics *289*
7.4 Data Acquisition and Rudimentary Signal Processing *289*
7.4.1 Introduction *289*
7.4.2 Hardware Considerations *290*
7.4.3 Dynamic Range, Accuracy and Linearity *290*
7.4.4 Sampling Rate and Signal Conditioning *291*
7.4.5 Digital Signal Conditioning and Storage *292*
7.5 Characterization, Calibration and Testing *292*
7.5.1 Introduction *292*
7.5.2 Characterizing SQUIDs *293*
7.5.2.1 Introduction *293*
7.5.2.2 Transfer Coefficient *293*
7.5.2.3 Effective Area of a Magnetometer *294*
7.5.2.4 Effective Volume of a Gradiometer *294*
7.5.2.5 SQUID Noise and Bandwidth Measurements *295*
7.5.2.6 Dynamic Range *296*
7.5.2.7 Slew Rate *296*
7.5.2.8 Nonlinearity *297*
7.5.3 Characterization in Various Magnetic Field Situations *298*
7.5.3.1 Introduction *298*
7.5.3.2 Field-applied (FA) Characterization *299*
7.5.3.3 Field-removed (FR) Characterization *299*
7.5.3.4 Hysteresis *301*
7.5.4 Calibration *301*
7.5.4.1 Setting up Calibration Fields *301*
7.5.4.2 Magnetometer and Gradiometer Calibration *305*
7.5.5 Testing and Practical Tips *305*
7.5.5.1 Drifts and Offsets *305*
7.5.5.2 SQUID or Flux Jumps *305*
7.5.5.3 Excess Noise *307*
7.5.5.4 Electronic Noise from Other Systems *307*
7.5.5.5 Adequate Shielding of the Cryostat *307*
7.5.5.6 Consequences of Cryogen Boil-off *308*
7.5.5.7 Mechanical Vibration *308*
7.5.5.8 Increase in Noise of the System Compared to a SQUID *309*
7.6 Conditions Imposed on SQUID Systems by the Environment and Applications *309*

7.6.1 Introduction *309*
7.6.2 Signals Acting on SQUID Systems *310*
7.6.3 Noise Acting on a SQUID System *311*
7.6.3.1 Environmental Noise in Stationary Applications *311*
7.6.3.2 Additional Noise in Mobile Instrumentation *315*
7.7 Noise Suppression *315*
7.7.1 Introduction *315*
7.7.2 Active Shielding *315*
7.7.3 Noise Cancellation by Primary Sensors *316*
7.7.4 Noise Cancellation Using References *319*
7.7.4.1 Introduction *319*
7.7.4.2 Static Systems *323*
7.7.4.3 Mobile Systems *330*
7.7.5 Noise Cancellation Without the References *332*
7.8 Signal and Noise Implications for the SQUID System Design *335*
7.8.1 Introduction *335*
7.8.2 Static SQUID Systems *335*
7.8.3 Mobile SQUID Systems *339*
7.8.4 Summary of Parameters *342*
7.9 Concluding Remarks and System Trends *344*

Appendix 1 *357*

Appendix 2 *367*

Index *383*